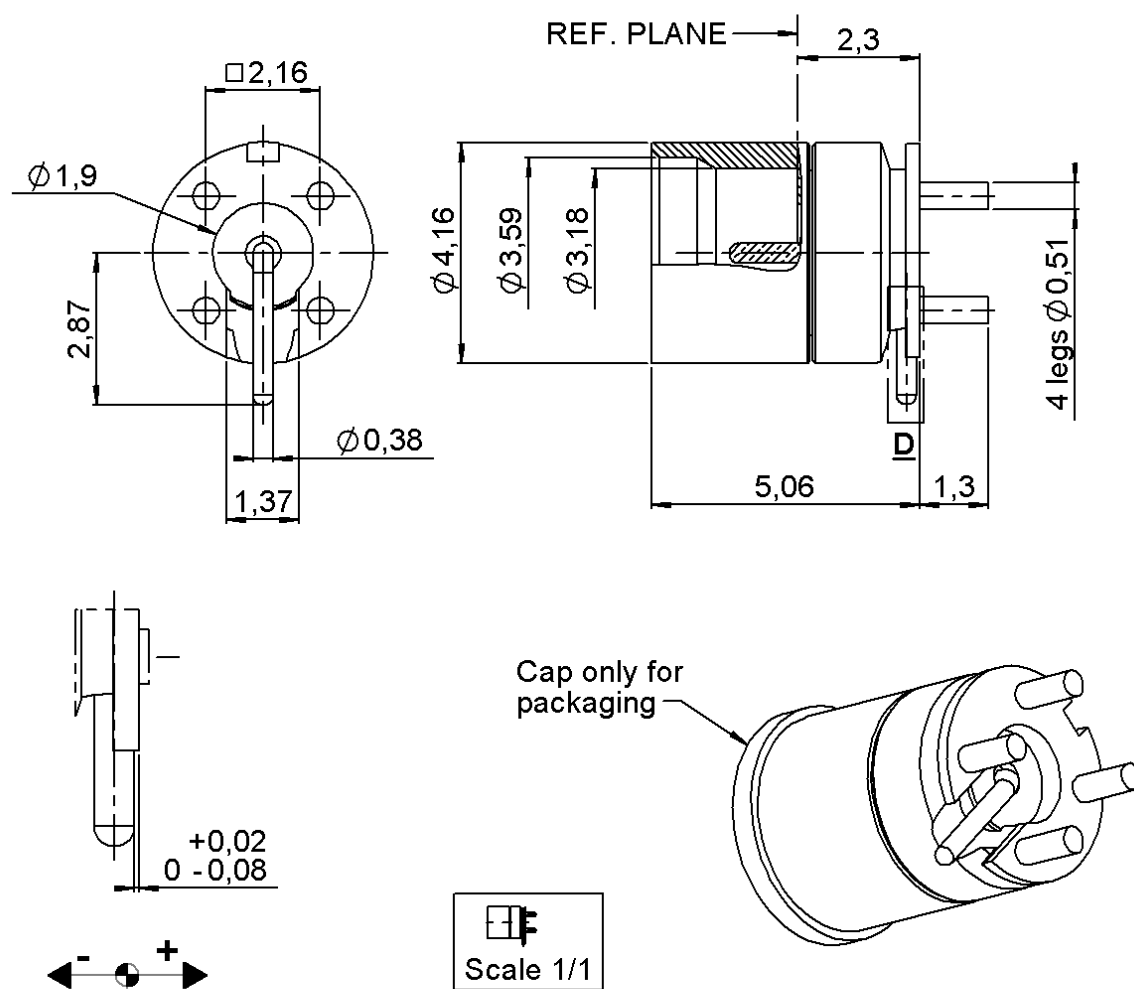


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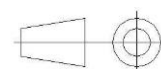
SERIES SMP

PART NUMBER R222428720



**DÉTAIL D**  
**ÉCHELLE 14 : 1**

All dimensions are in mm. Tolerances according ISO 2768 m-H



COMPONENTS	MATERIALS	PLATING (μm)
Body	BRASS	GOLD 0.2 MAX OVER NICKEL2
Others parts		
Outer contact	STAINLESS STEEL	GOLD 0.1 TO 0.4 OVER NICKEL2
Insulator	PTFE	
Gasket		
Center contact	BERYLLIUM COPPER	TIP : GOLD 1.3 OVER NICKEL2
-	-	-REAR : GOLD FLASH OVER NICKEL2
-	-	-

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### PACKAGING

Standard	Unit	Other
<b>100</b>	<b>Contact us</b>	<b>Contact us</b>

### ELECTRICAL CHARACTERISTICS

Impedance		<b>50</b>	Ω
Frequency		<b>0-40*</b>	GHz
VSWR	<b>1.20**</b>	<b>+</b>	<b>0,0000</b> x F(GHz) Maxi
Insertion loss		<b>0.12*</b>	√F(GHz) dB Maxi
RF leakage	- (	<b>NA</b>	- F(GHz) dB Maxi
Voltage rating		<b>335</b>	Veff Maxi
Dielectric withstanding voltage		<b>500</b>	Veff mini
Insulation resistance		<b>5000</b>	MΩ mini

### MECHANICAL CHARACTERISTICS

Center contact retention			
Axial force – Mating End		<b>6.7</b>	N mini
Axial force – Opposite end		<b>NA</b>	N mini
Torque		<b>NA</b>	N.cm mini
Recommended torque			
Mating		<b>NA</b>	N.cm
Panel nut		<b>NA</b>	N.cm
Mating life		<b>1000</b>	Cycles mini
Weight		<b>0,2900</b>	g

### ENVIRONMENTAL

Operating temperature	<b>-65/+165</b>	°C
Hermetic seal	<b>NA</b>	Atm.cm3/s
Panel leakage	<b>NA</b>	

### SPECIFICATION

### OTHER CHARACTERISTICS

Assembly instruction:

Others:

**\*Coaxial transmission line only**

**\*\*DC-12.4GHz - Performances strongly depends on layout PCB material**

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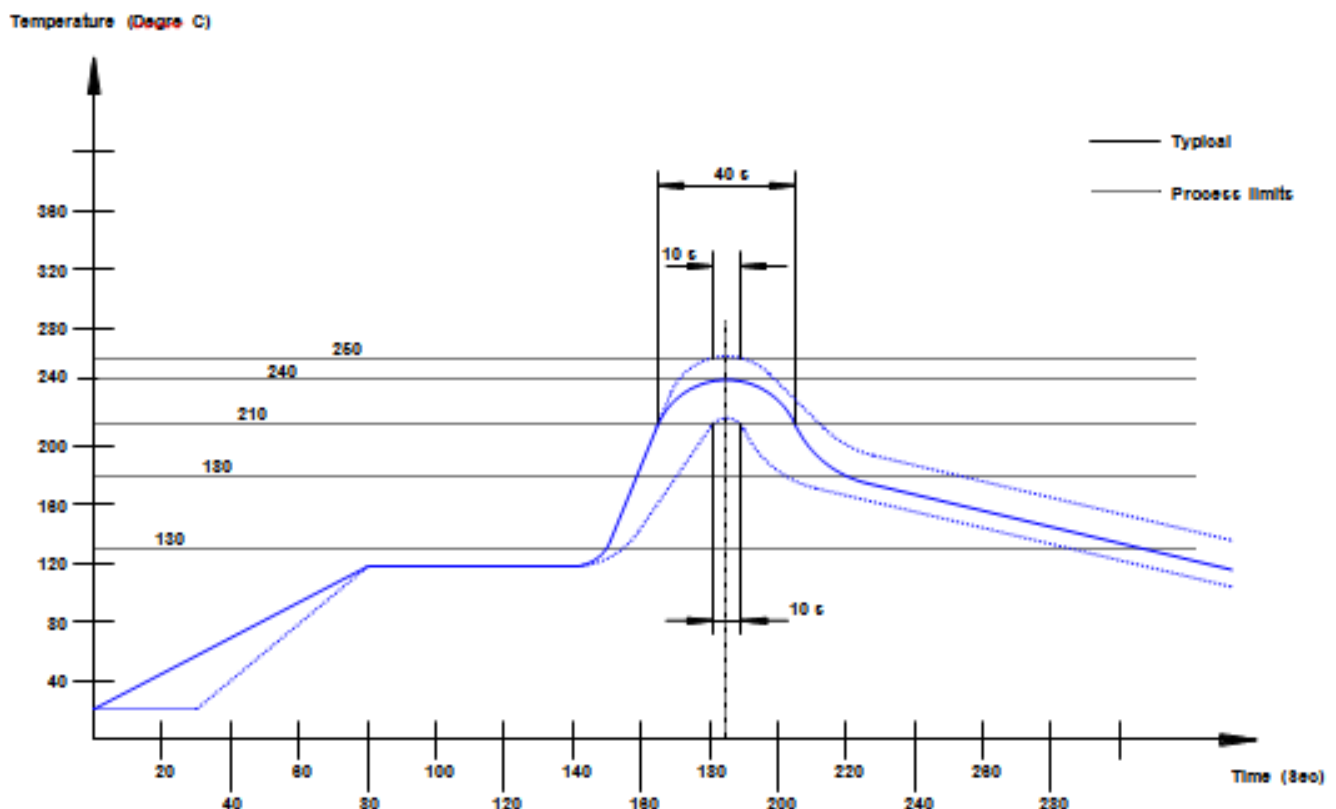
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### SOLDER PROCEDURE

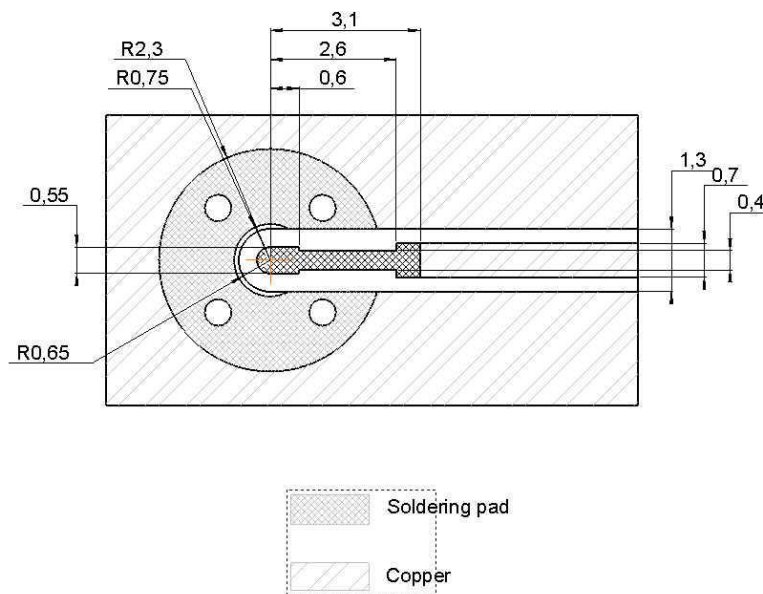
1. Deposit solder paste 'Sn Pb 60-40' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150  $\mu\text{m}$ .  
Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.  
Video camera is preferred to check the positioning of the component. Adhesive agents are forbidden on the receptacle.
3. Soldering by infra-red reflow.
4. Cleaning of printed circuit boards.
5. Checking of solder joints and position of the component by visual inspection.

### TEMPERATURE PROFIL

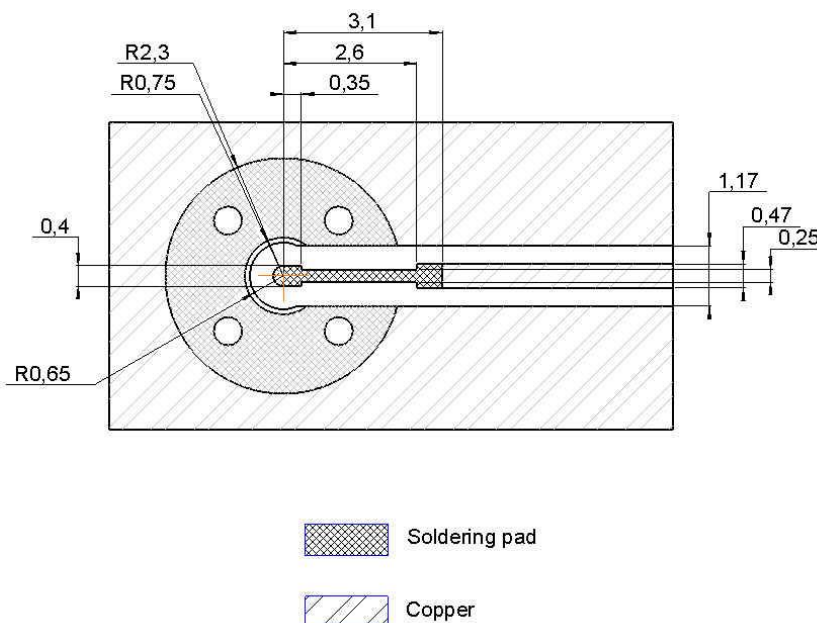


## RECOMMENDED PAD DIMENSIONS:

Substrate: RT5880 thickness 0.254mm, with copper layer 35µm on both sides :  
Add vias between both sides along upper ground plane according to engineering practise



Substrate: RO4350 thickness 0.254mm, with copper layer 35µm on both sides :  
Add vias between both sides along upper ground plane according to engineering practise



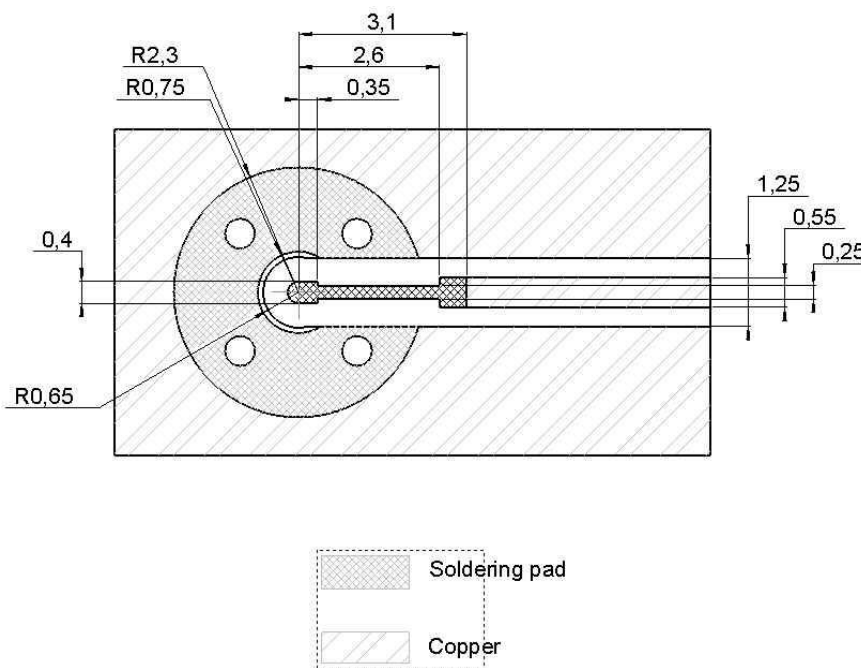
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Substrate: RO6002 thickness 0.254mm, with copper layer 35µm on both sides :  
Add vias between both sides along upper ground plane according to engineering practise



### SHADOW FOR VIDEO CAMERA

